



GaAs pHEMT MMIC ½ WATT POWER AMPLIFIER, 22 - 26.5 GHz

Typical Applications

The HMC863LP4E is ideal for:

- Point-to-Point Radios
- Point-to-Multi-Point Radios
- VSAT
- Military & Space

Features

Saturated Output Power: up to +27.5 dBm @ 15% PAE

High Output IP3: +33 dBm

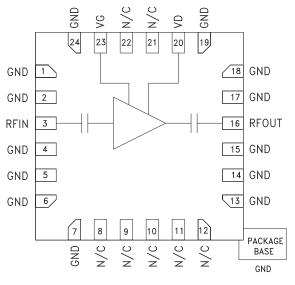
High Gain: 21.5 dB

DC Supply: +6V @ 350mA

No External Matching Required

24 Lead 4x4 mm SMT Package: 16 mm²

Functional Diagram



General Description

The HMC863LP4E is a three stage GaAs pHEMT MMIC ½ Watt Power Amplifier which operates between 22 and 26.5 GHz. The HMC863LP4E provides 21.5 dB of gain, +27.5 dBm of saturated output power and 15% PAE from a +6V supply. High output IP3 makes the HMC863LP4E ideal for point-to-point and point-to-multi-point radio systems as well as VSAT applications. The RF I/Os are DC blocked and matched to 50 Ohms for ease of integration into higher level assemblies. The HMC863LP4E can also be operated from a 5V supply with only a slight decrease in output power & IP3.

Electrical Specifications, $T_A = +25^{\circ}$ C, Vdd = Vdd1 = Vdd2 = +6V, Idd = 350mA [1]

| Parameter | Min. | Тур. | Max. | Units |
|---|------|-----------|------|--------|
| Frequency Range | | 22 - 26.5 | | GHz |
| Gain | 19 | 21.5 | | dB |
| Gain Variation Over Temperature | | 0.032 | | dB/ °C |
| Input Return Loss | | 11 | | dB |
| Output Return Loss | | 15 | | dB |
| Output Power for 1 dB Compression (P1dB) | 22 | 24.5 | | dBm |
| Saturated Output Power (Psat) | | 27 | | dBm |
| Output Third Order Intercept (IP3) ^[2] | | 33 | | dBm |
| Total Supply Current (Idd) | | 350 | 380 | mA |

^[1] Adjust Vgg between -2 to 0V to achieve Idd = 350mA typical.

^[2] Measurement taken at +6V @ 350mA, Pout / Tone = +14 dBm

GaAs pHEMT MMIC 1/2 WATT

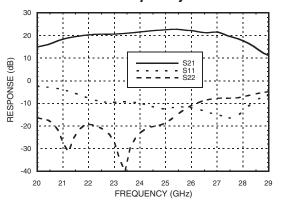
POWER AMPLIFIER, 22 - 26.5 GHz



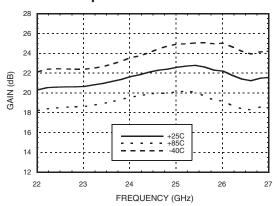
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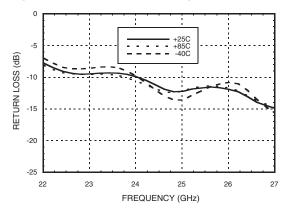
Broadband Gain & Return Loss vs. Frequency



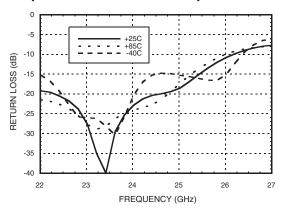
Gain vs. Temperature



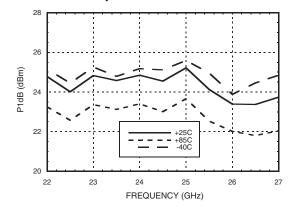
Input Return Loss vs. Temperature



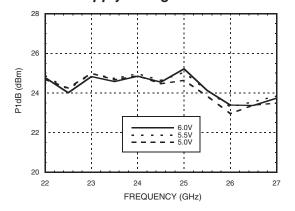
Output Return Loss vs. Temperature



P1dB vs. Temperature



P1dB vs. Supply Voltage

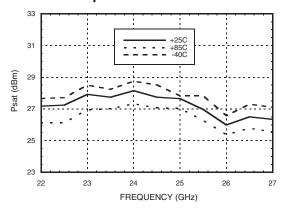




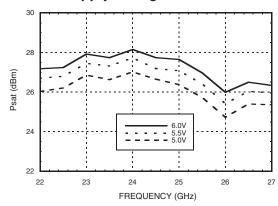


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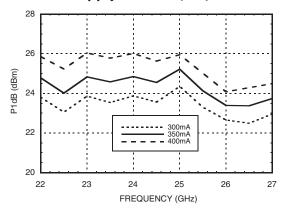
Psat vs. Temperature



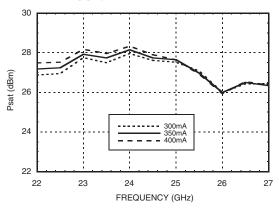
Psat vs. Supply Voltage



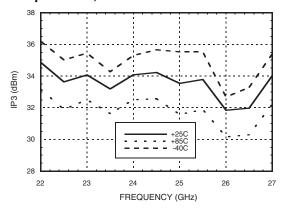
P1dB vs. Supply Current (Idd)



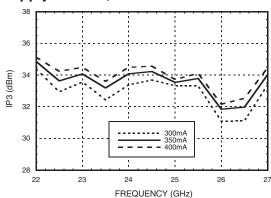
Psat vs. Supply Current (Idd)



Output IP3 vs. Temperature, Pout/Tone = +14 dBm



Output IP3 vs.
Supply Current, Pout/Tone = +14 dBm



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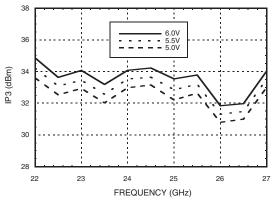
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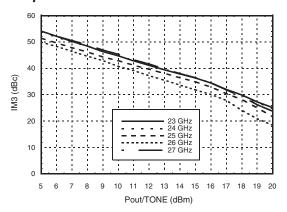
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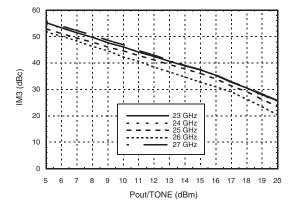
Output IP3 vs. Supply Voltage, Pout/Tone = +14 dBm



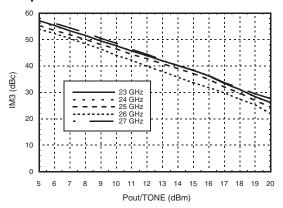
Output IM3 @ Vdd = +5V



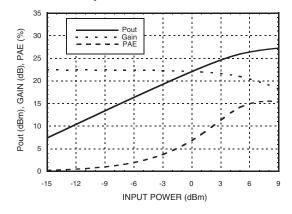
Output IM3 @ Vdd = +5.5V



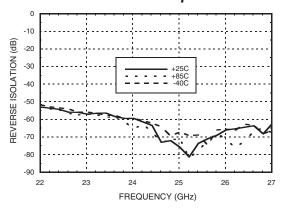
Output IM3 @ Vdd = +6V



Power Compression @ 25 GHz



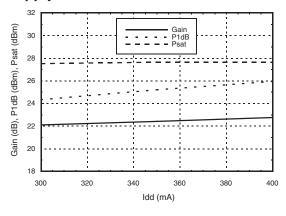
Reverse Isolation vs. Temperature





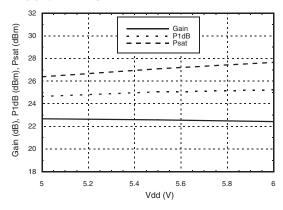


Gain & Power vs. Supply Current @ 25 GHz

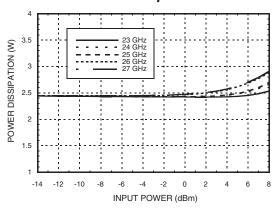


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Gain & Power vs. Supply Voltage @ 25 GHz



Power Dissipation



Absolute Maximum Ratings

| Drain Bias Voltage (Vd) | 6.3V |
|--|----------------|
| RF Input Power (RFIN) | +26 dBm |
| Channel Temperature | 150 °C |
| Continuous Pdiss (T= 85 °C) (derate 37 mW/°C above 85 °C) | 2.52 W |
| Thermal Resistance (channel to ground paddle) | 26.9 C/W |
| Storage Temperature | -65 to +150 °C |
| Operating Temperature | -55 to +85 °C |
| ESD Sensitivity (HBM) | Class 0, 150V |

Typical Supply Current vs. Vdd

| Vdd (V) | ldd (mA) |
|---------|----------|
| +5.0 | 350 |
| +5.5 | 350 |
| +6.0 | 350 |

Note: Amplifier will operate over full voltage ranges shown above Vgg adjusted to achieve Idd = 350mA at +5.5V



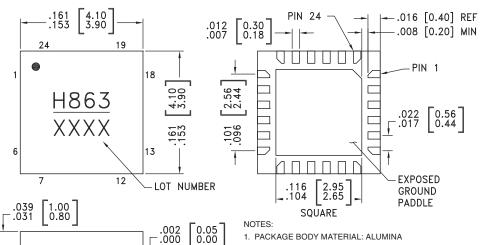
ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS





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Outline Drawing



PLANE

-C-

1. PACKAGE BODY MATERIAL: ALUMINA

BOTTOM VIEW

- 2. LEAD AND GROUND PADDLE PLATING: 30-80 MICROINCHES GOLD OVER 50 MICROINCHES MINIMUM NICKEL.
- 3. DIMENSIONS ARE IN INCHES [MILLIMETERS].
- 4. LEAD SPACING TOLERANCE IS NON-CUMULATIVE
- 5. PACKAGE WARP SHALL NOT EXCEED 0.05mm DATUM -C-
- 6. ALL GROUND LEADS AND GROUND PADDLE MUST BE SOLDERED TO PCB RF GROUND.
- 7. CLASSIFIED AS MOISTURE SENSITIVITY LEVEL (MSL) 1.

Package Information

.003[0.08] C

| Part Number | Package Body Material | Lead Finish | MSL Rating | Package Marking [1] |
|-------------|--|---------------|------------|---------------------|
| HMC863LP4E | RoHS-compliant Low Stress Injection Molded Plastic | 100% matte Sn | MSL1 [2] | H863 XXXX |

^{[1] 4-}Digit lot number XXXX

Pin Descriptions

| Pin Number | Function | Description | Interface Schematic |
|--|----------|--|---------------------|
| 1, 2, 4 - 7, 12 - 15, 17 - 19, 24 Package Bottom | GND | Ground pins and package bottom must be connected to RF/DC ground. | GND = |
| 3 | RFIN | This pin is AC coupled and matched to 50 Ohms. | RFIN ○── |
| 8 - 11 | N/C | The pins are not connected internally; however, all data shown herein was measured with these pins connected to RF/DC ground externally. | |
| 16 | RFOUT | This pin is AC coupled and matched to 50 Ohms. | — |
| 20 | Vd | Drain bias for amplifier. External 100 pF, 0.1 μF and 4.7 μF bypass capacitors are required. | OVd |
| 23 | Vg | Gate control for PA. Adjust Vg to achieve recommended bias current. External 100 pF, 0.1 μF and 4.7 μF bypass capacitors are required. | vg o |

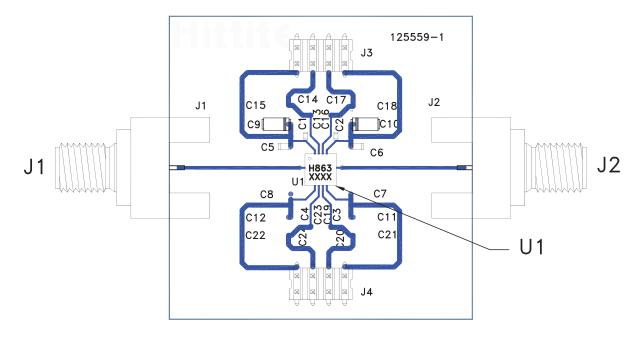
^[2] Max peak reflow temperature of 260 °C





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Evaluation PCB



List of Materials for Evaluation PCB 130560 [1]

| Item | Description | |
|---------|------------------------------|--|
| J1 - J2 | 2.9 mm Connectors | |
| J3 - J4 | DC Pins | |
| C1, C2 | 100 pF Capacitors, 0402 Pkg. | |
| C6 | 10 kpF Capacitor, 0402 Pkg | |
| C10 | 4.7 μF Capacitor, 0402 Pkg. | |
| U1 | HMC863LP4E Power Amplifier | |
| PCB [2] | 125559 Evaluation PCB | |

^[1] Reference this number when ordering complete evaluation PCB

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50 Ohm impedance while the package ground leads and exposed paddle should be connected directly to the ground plane similar to that shown. A sufficient number of via holes should be used to connect the top and bottom ground planes. The evaluation board should be mounted to an appropriate heat sink. The evaluation circuit board shown is available from Hittite upon request.

^[2] Circuit Board Material: Rogers 4350 or Arlon FR4





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Application Circuit

